SLLS513A - AUGUST 2001 - REVISED MARCH 2004

- Single-Chip and Single-Supply Interface for Two IBM™ PC/AT Serial Ports
- Meet or Exceed the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operate With 3-V to 5.5-V V_{CC} Supply
- Always-Active Noninverting Receiver **Output (ROUT2) Per Port**
- Operate Up To 250 kbit/s
- Low Standby Current . . . 1 µA Typical
- External Capacitors . . . $4 \times 0.22 \mu F$
- Accept 5-V Logic Input With 3.3-V Supply
- Allow for Flexible Power Down of Either **Serial Port**
- **Serial-Mouse Driveability**
- **RS-232 Bus-Pin ESD Protection Exceeds** ±15 kV Using Human-Body Model (HBM)
- **Applications**
 - Battery-Powered Systems, Notebooks, Laptops, Palmtop PCs, and Hand-Held **Equipment**

description/ordering information

The SN65C23243 and SN75C23243 consist of two ports, each containing three line drivers and five line receivers, and a dual charge-pump circuit with ±15-kV ESD protection pin to pin (serial-port

RIN5A 48 ROUT5A 47 NOUT4A RIN4A II 2 RIN3A [] 3 46 ROUT3A RIN2A 4 45 ∏ ROUT2A RIN1A [15 44 ROUT1A INVA 6 43 ROUT2A DOUT3A Π_7 42 **∏** DIN3A 41 DIN2A DOUT2A 8 DOUT1A [] 9 40 DIN1A FORCEOFFA 1 10 39 T FORCEON 38 N-C2-37 N+ C2+ **∏** 12 GND II 13 36 ∏ C1+ 35 C1-14 Vcc 4 FORCEOFFB [] 15 34 GND DOUT1B 16 33 **∏** DIN1B DOUT2B 1 17 32 DIN2B DOUT3B [] 18 31 DIN3B **INVB 1** 19 30 ROUT2B RIN1B [] 20 29 ROUT1B RIN2B [] 21 28 ROUT2B RIN3B **1**22 27 NOUT3B RIN4B [] 23 26 NOUT4B RIN5B **1**24 25 ∏ ROUT5B

DGG OR DL PACKAGE (TOP VIEW)

connection pins, including GND). These devices meet the requirements of TIA/EIA-232-F and provide the electrical interface between an asynchronous communication controller and the serial-port connector. This combination of drivers and receivers matches that needed for two typical serial ports used in an IBM PC/AT, or compatible. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, these devices include an always-active noninverting output (ROUT2) per port, which allows applications using the ring indicator to transmit data while the devices are powered down. The devices operate at data signaling rates up to 250 kbit/s and a maximum of 30-V/µs driver output slew-rate.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0000 (DL)	Tube of 25	SN75C23243DL	75000040
-0°C to 70°C	SSOP (DL)	Reel of 1000	SN75C23243DLR	75C23243
	TSSOP (DGG)	Reel of 2000	SN75C23243DGGR	75C23243
	000D (DL)	Tube of 25	SN65C23243DL	05000040
-40°C to 85°C	SSOP (DL)	Reel of 1000	SN65C23243DLR	65C23243
	TSSOP (DGG)	Reel of 2000	SN65C23243DGGR	65C23243

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

Flexible control options for power management are available when either or both serial ports are inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs of its respective port are disabled. If FORCEOFF is set low, both drivers and receivers (except ROUT2) are shut off, and the supply current is reduced to 1 µA. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur.

Auto-powerdown can be disabled when FORCEON and FORCEOFF are high and should be done when driving a serial mouse. With auto-powerdown enabled, the RS-232 port is activated automatically when a valid signal is applied to any respective receiver input. The INV output is used to notify the user if an RS-232 signal is present at any receiver input. INV is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30 μs. INV is low (invalid data) if all receiver input voltages are between –0.3 V and 0.3 V for more than 30 μs. Refer to Figure 5 for receiver input levels.

Function Tables

EACH DRIVER (each port)

		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

H = high level, L = low level, X = irrelevant, Z = high impedance

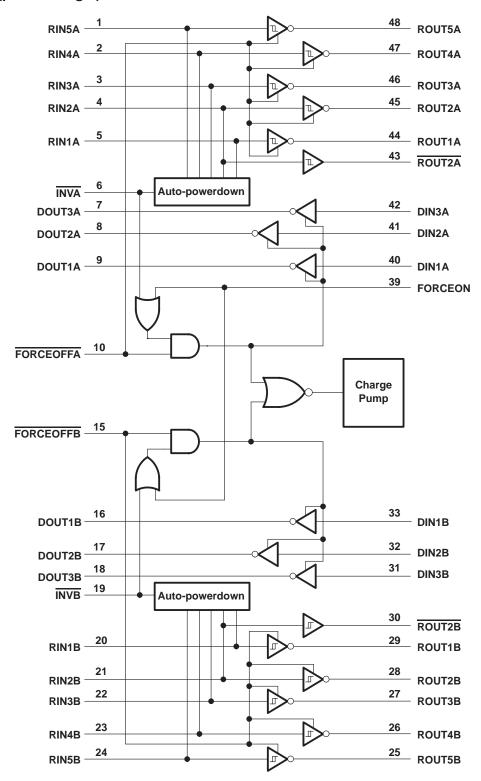
EACH RECEIVER (each port)

			(******	,		
	INPUTS			OUTP	UTS	
RIN2	RIN1, RIN3–RIN5	FORCEOFF	VALID RIN RS-232 LEVEL	ROUT2	ROUT	RECEIVER STATUS
L	Χ	L	Х	L	Z	Powered off while
Н	Χ	L	X	Н	Z	ROUT2 is active
L	L	Н	Yes	L	Н	
L	Н	Н	Yes	L	L	Normal operation with
Н	L	Н	Yes	Н	Н	auto-powerdown
Н	Н	Н	Yes	Н	L	disabled/enabled
Open	Open	Н	No	L	Н	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

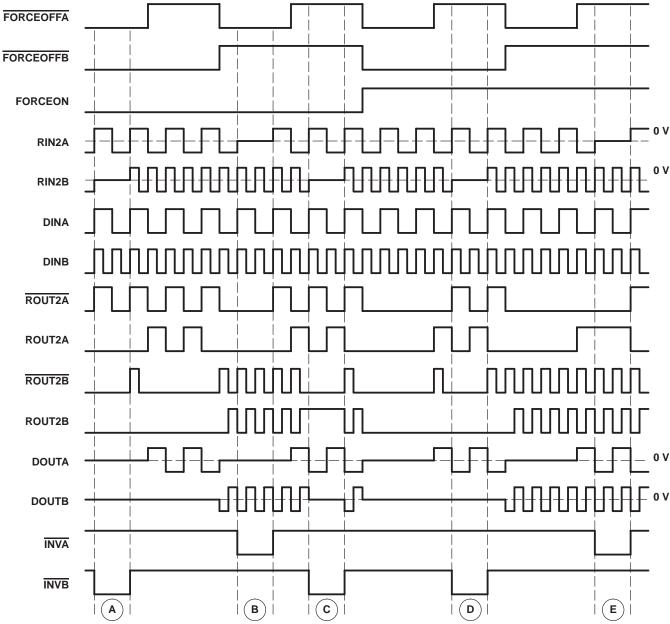


logic diagram (positive logic)



timing

Figure 1 shows how the two independent serial ports can be enabled or disabled. As shown by the logic states, depending on the FORCEOFF, FORCEON, and receiver input levels, either port can be powered down. Intermediate receiver input levels indicate a 0-V input. Also, it is assumed a pulldown resistor to ground is used for the receiver outputs. The INV pin goes low when its respective receiver input does not supply a valid RS-232 level. For simplicity, voltage levels, timing differences, and input/output edge rates are not shown.



NOTES: A. Ports A and B manually powered off

- B. Port A manually powered off, port B in normal operation with auto-powerdown enabled
- C. Port B powered off by auto-powerdown, port A in normal operation with auto-powerdown enabled
- D. Port A in normal operation with auto-powerdown disabled, port B manually powered off
- E. Ports A and B in normal operation with auto-powerdown disabled

Figure 1. Timing Diagram



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	
Negative output supply voltage, V- (see Note 1)	0.3 V to -7 V
Supply voltage difference, V+ – V– (see Note 1)	
Input voltage range, V _I : Driver (FORCEOFF, FORCEON)	–0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, VO: Driver	13.2 V to 13.2 V
Receiver (INV)	0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DGG package	70°C/W
DL package	63°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{sta}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 7)

			MIN	NOM	MAX	UNIT
Owner become to make	unnly voltage		3	3.3	3.6	
Supply voltage		V _{CC} = 5 V	4.5	5	5.5	V
Debugger and a set and blink bound in more configuration. M	DIN FORCES FORCES	V _{CC} = 3.3 V	2			
Driver and control high-level input voltage, V _{IH}	DIN, FORCEOFF, FORCEON	V _{CC} = 5 V	2.4			V
Driver and control low-level input voltage, V _{IL}	DIN, FORCEOFF, FORCEON				8.0	V
Driver and control input voltage, V _I	DIN, FORCEOFF, FORCEON		0		5.5	V
Receiver input voltage, V _I	RIN		-25		25	V
Organization from a state or a section. T		SN75C23243	0		70	00
Operating free-air temperature, TA		SN65C23243	-40		85	°C

NOTE 4: Test conditions are C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 7)

PARAMETER		TEST CONDITIONS	MIN	TYP‡	MAX	UNIT	
П	Input leakage current	FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown disabled	No load, FORCEOFF and FORCEON at V _{CC}		0.6	2	mA
Icc	Supply current	Powered off	No load, FORCEOFF at GND		1	20	
.00	(T _A = 25°C)	Auto-powerdown enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	20	μΑ

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 7)

	PARAMETER	TE	ST CONDITION	S	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	All DOUT at $R_L = 3 \text{ k}\Omega$ to	o GND		5	5.4		V
VOL	Low-level output voltage	All DOUT at $R_L = 3 \text{ k}\Omega$ to	o GND		-5	-5.4		V
VO	Output voltage (mouse driveability)	DIN1 = DIN2 = GND, DII 3-k Ω to GND at DOUT3,		T2 = −2.5 mA	±5			V
ΊΗ	High-level input current	VI = VCC				±0.01	±1	μΑ
Ι _Ι Γ	Low-level input current	V _I at GND				±0.01	±1	μΑ
	0	VCC = 3.6 V,	VO = 0 V					•
los	Short-circuit output current‡	V _{CC} = 5.5 V,	VO = 0 V			±35	±60	mA
r _o	Output resistance	V_{CC} , V+, and V- = 0 V,	V _O = ±2 V		300	10M		Ω
	Output lookage ourrant	FORCEOFF = GND	$V_0 = \pm 12 V$,	V _{CC} = 3 V to 3.6 V			±25	
loff	Output leakage current	FURGEOFF = GND	$V_0 = \pm 10 \text{ V},$	V _{CC} = 4.5 V to 5.5 V			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 7)

	PARAMETER	TEST CONDITIONS			TYP†	MAX	UNIT
	Maximum data rate	C _L = 1000 pF, One DOUT switching,	$R_L = 3 k\Omega$, See Figure 1	250			kbit/s
tsk(p)	Pulse skew§	C _L = 150 pF to 2500 pF	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$ See Figure 2		100		ns
SR(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	C _L = 150 pF to 1000 pF	6		30	V/µs
SK(II)	(see Figure 1)	$R_L = 3 k\Omega$ to $7 k\Omega$	C _L = 150 pF to 2500 pF	4		30	ν/μδ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

§ Pulse skew is defined as $|tp_{LH} - tp_{HL}|$ of each channel of the same device. NOTE 4: Test conditions are C1–C4 = 0.22 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



^{\$\}frac{1}{2}\$ Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 7)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Vон	High-level output voltage	I _{OH} = -1 mA	V _{CC} – 0.6 V	V _{CC} – 0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
.,	Partition and an investment through a behavior	VCC = 3.3 V		1.6	2.4	.,
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 5 V		1.9	2.4	V
.,	Manager and a Constitutional and college	V _{CC} = 3.3 V	0.6	1.1		
V _{IT} _	Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.4		V
V _{hys}	Input hysteresis (V _{IT+} – V _{IT} _)			0.5		V
l _{off}	Output leakage current (except ROUT2B)	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.

NOTE 4: Test conditions are C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 7)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	C _I = 150 pF, See Figure 4		150		ns
tPHL	Propagation delay time, high- to low-level output	CL = 150 pF, See Figure 4		150		ns
ten	Output enable time			200		ns
^t dis	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 5}$		200		ns
t _{sk(p)}	Pulse skew [‡]	See Figure 4		50		ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

‡ Pulse skew is defined as $|tp_{LH} - tp_{HL}|$ of each channel of the same device. NOTE 4: Test conditions are C1–C4 = 0.22 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
V _{T+(valid)}	Receiver input threshold for INV high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}		2.7	V
V _T –(valid)	Receiver input threshold for INV high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7		V
V _T (invalid)	Receiver input threshold for INV low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3	0.3	V
VOH	INV high-level output voltage	I _{OH} = -1 mA, FORCEON = GND, FORCEOFF = V _{CC}	V _{CC} - 0.6		V
V _{OL}	INV low-level output voltage	I _{OL} = 1.6 mA, FORCEON = GND, FORCEOFF = V _{CC}		0.4	V

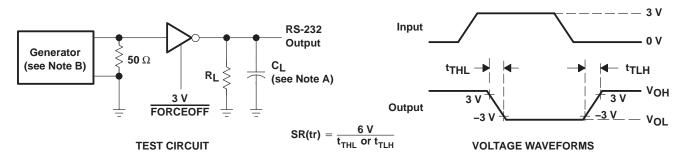
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

	PARAMETER	MIN	TYP [†]	MAX	UNIT
^t valid	Propagation delay time, low- to high-level output		1		μs
^t invalid	Propagation delay time, high- to low-level output		30		μs
t _{en}	Supply enable time		100		μs

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.



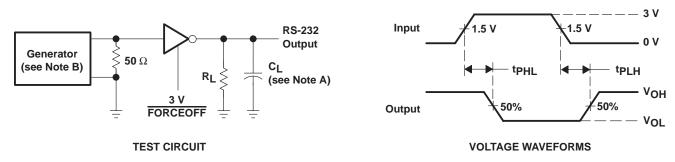
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

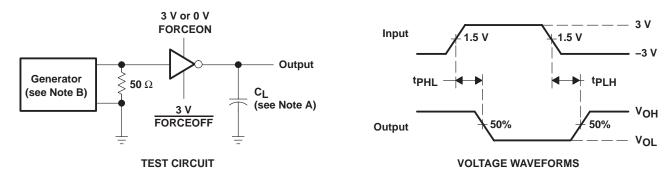
Figure 2. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_Q = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 3. Driver Pulse Skew



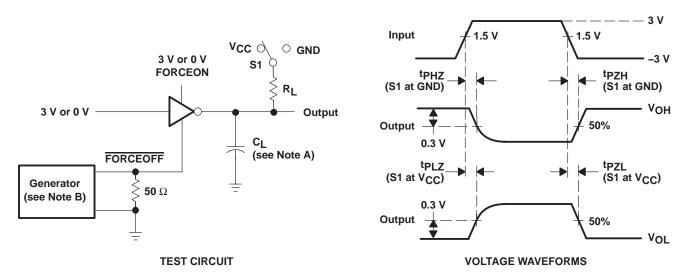
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_0 = 50 \ \Omega$, 50% duty cycle, $t_r \le 10 \ ns$, $t_f \le 10 \ ns$.

Figure 4. Receiver Propagation Delay Times



PARAMETER MEASUREMENT INFORMATION



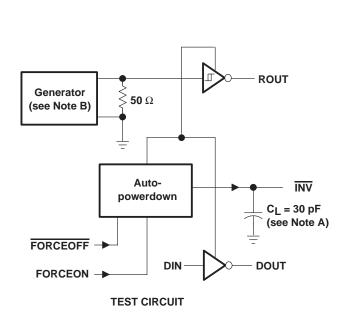
NOTES: A. C_L includes probe and jig capacitance.

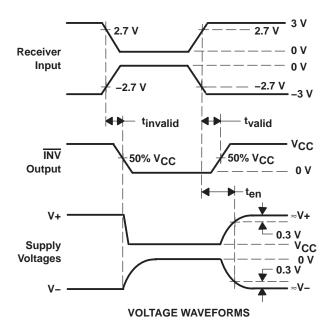
- B. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.
- C. tpLz and tpHz are the same as tdis.
- D. tpZL and tpZH are the same as ten.

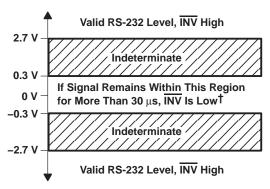
Figure 5. Receiver Enable and Disable Times



PARAMETER MEASUREMENT INFORMATION







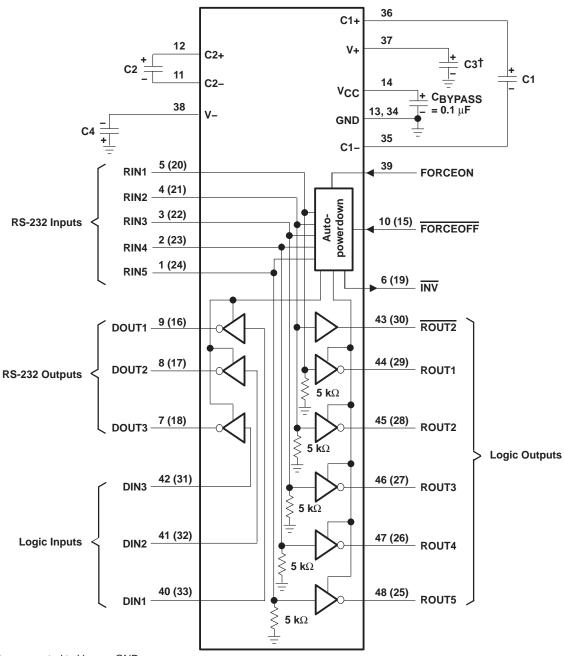
 † Auto-powerdown disables drivers and reduces supply current to 1 $\mu A.$

NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns. $t_f \le 10$ ns.

Figure 6. INV Propagation Delay Times and Supply Enabling Time

APPLICATION INFORMATION



 $\ensuremath{^{\dagger}}\xspace \text{C3}$ can be connected to $\ensuremath{\text{V}_{CC}}\xspace$ or GND.

NOTES: A. Resistor values shown are nominal.

B. Numbers in parentheses are for B section.

V_{CC} vs CAPACITOR VALUES

VCC	C1	C2, C3, and C4			
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.22 μF 0.047 μF 0.22 μF	0.22 μF 0.33 μF 1 μF			

Figure 7. Typical Operating Circuit and Capacitor Values



11-Nov-2025

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	(1)	(2)			(3)	(4)	(5)		(6)
SN65C23243DGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65C23243
SN65C23243DGGR.A	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65C23243
SN65C23243DLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65C23243
SN65C23243DLR.A	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65C23243
SN75C23243DGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C23243
SN75C23243DGGR.A	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C23243
SN75C23243DLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C23243
SN75C23243DLR.A	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C23243

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

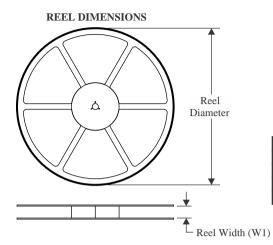
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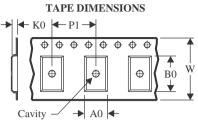
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

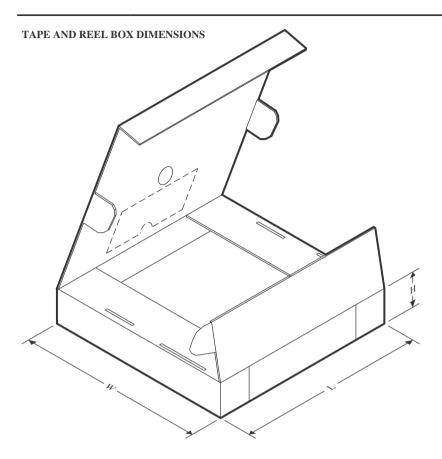


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65C23243DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN65C23243DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN75C23243DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN75C23243DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1



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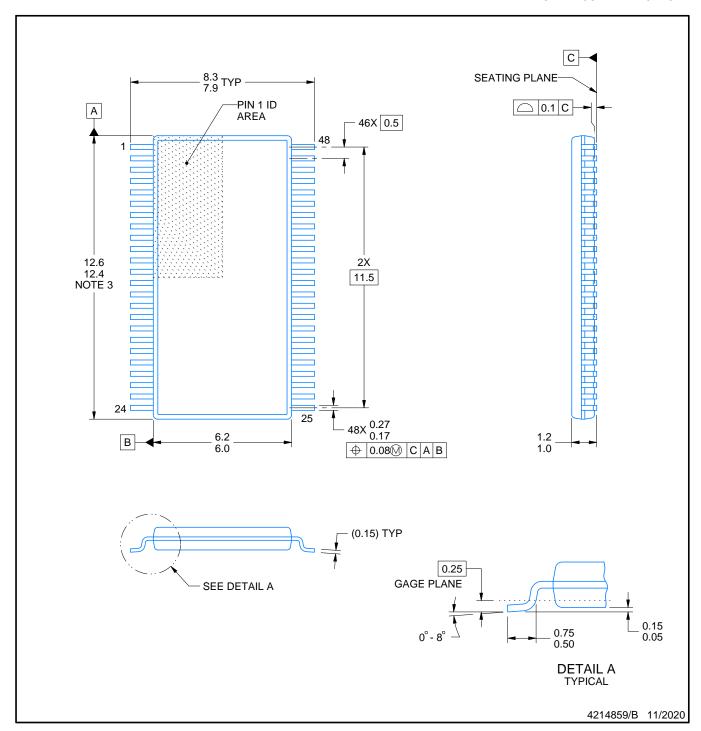


*All dimensions are nominal

7 III danielielie die Herrina.									
	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	SN65C23243DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0	
	SN65C23243DLR	SSOP	DL	48	1000	356.0	356.0	53.0	
	SN75C23243DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0	
	SN75C23243DLR	SSOP	DL	48	1000	356.0	356.0	53.0	



SMALL OUTLINE PACKAGE



NOTES:

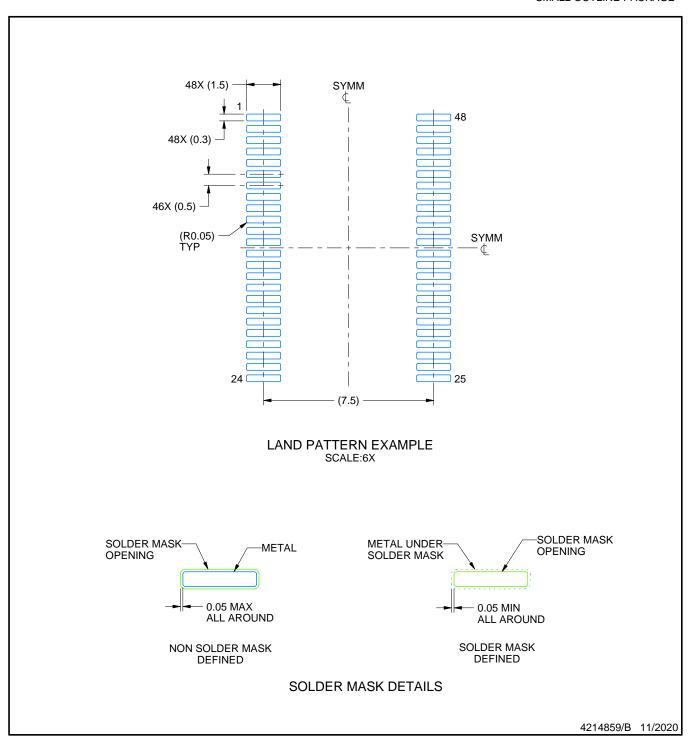
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

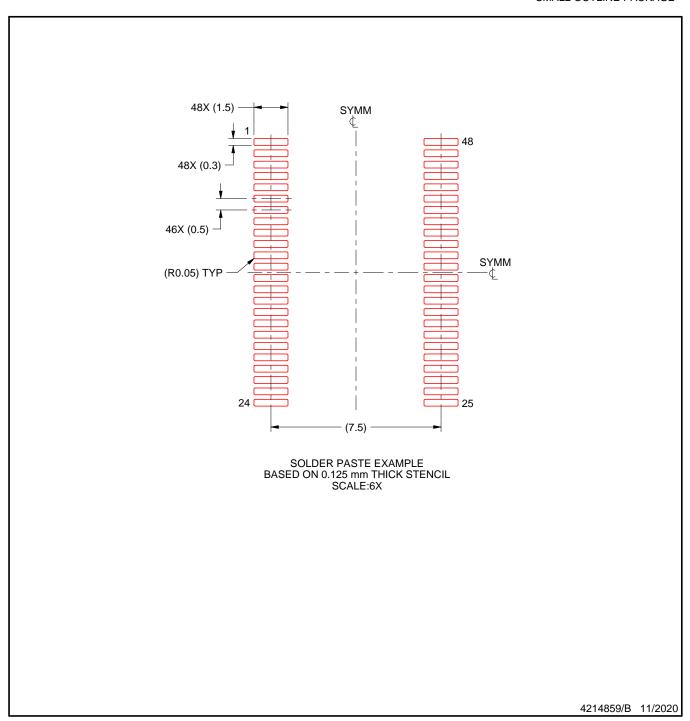


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

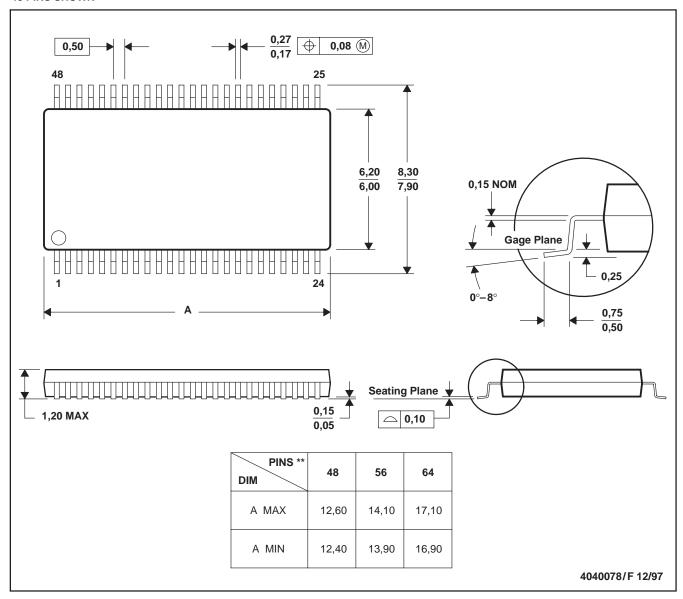
- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

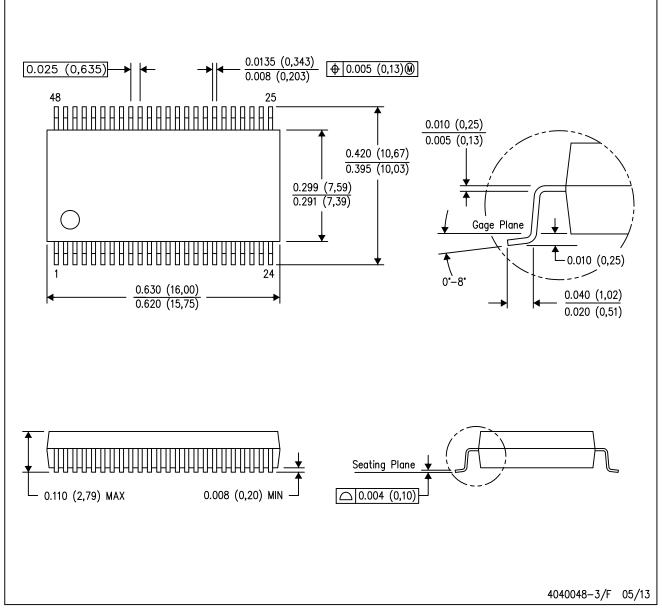
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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